

**Amendments to th Specification**

Please replace the title with the following new title:

**Methods of Forming Dielectric Materials and Methods of Processing Semiconductor  
Substrates**

At page 1 following the title, please add the following new paragraph:

**Cross Reference to Related Application**

This patent application is a continuation application of serial number 09/602,381,  
filed June 22, 2000, now U.S. Patent No. 6,649,543.